	7	6	5	4	3	2		
	NOTES: UNLESS OTHERWISE SPECIFIED 1 Rohs Compliant Assembly Required. Assemble Per IPC—A— 2 AQUEOUS BASED CLEANING AFTER SOLDER FOR ALL COMPONEI Rohs Solder Process is acceptable. 3 ITEM IDENTIFICATION: MARK REVISION NUMBER OF THIS DRAWING	NTS IS PREFERRED, NO—CLEAN				REV DESCRIPTION O1 INITIAL RELEASE O2 MODIFICATIONS FOR ALPHA 2 REL	07/21/2016	
В								В
				Handle Interconnect 100872 • REV •				
				ASSEMBLY TOP				
					UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS PROPRIETARY AND TOLERANCES: CONFIDENTIAL .XX ± 0.25	F. PRICE O9/23/2016 1511 Six ENGINEER D. BRUEY MECH ENG	SYNAPSE Ath Ave. Suite 300, Seattle, WA 98101 206.381.0898 PRINTED CIRCUIT BOARD ASSEMBLY Handle Interconnect	
					AND CONFIDENTIAL THE INFORMATION CONTAINED IN THIS DRAWING IS PROPRIETARY AND RESTRICTED. ANY REPRODUCTION IN PART OR WHOLE WITHOUT THE EXPRESS WRITTEN PERMISSION OF THE OWNER IS PROHIBITED TOLERANCES: .XX	A. DAHLGREN DWG NO SIZE DWG NO SCALE:4:1	600—100872 02 SHEET 1 OF 2	
	7	6	5	4	3	2		

